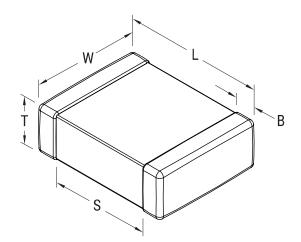


C1206X302MATAC7210

SMD Comm X8G HT150C Flex, Ceramic, 3,000 pF, 20%, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1206, 1.5 mm



Click here for the 3D model.

10000

General Information	
Series	SMD Comm X8G HT150C Flex
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	15 mg
Shelf Life	78 Weeks
MSL	1

ions		Specifications	
e	1206	Capacitance	
	3.3mm +/-0.4mm	Measurement Condi	
	1.6mm +/-0.35mm	Tolerance	
	0.78mm +/-0.20mm	Voltage DC	
	1.5mm MIN	Dielectric Withstand	
	0.6mm +/-0.25mm	Temperature Range	
		Temp. Coefficient	
ing Specifications		Capacitance Change	
ng	T&R, 330mm, Plastic Tape	Reference to +25°C a	

Capacitance	3,000 pF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	20%
Voltage DC	250 VDC
Dielectric Withstanding Voltage	625 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

Insulation Resistance

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

Dimensi

Chip Size

Packagi

Packaging

Packaging Quantity

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